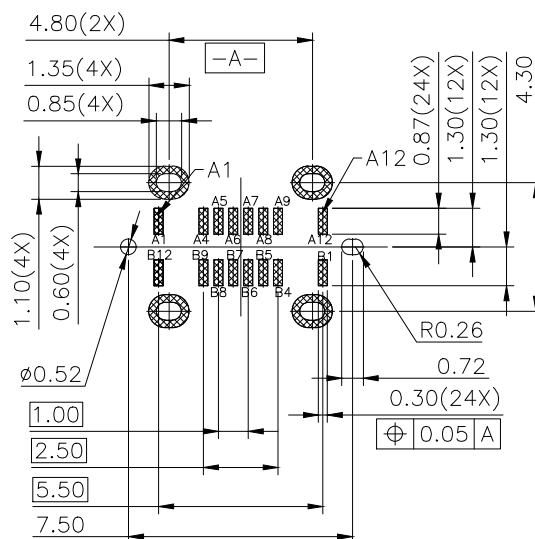
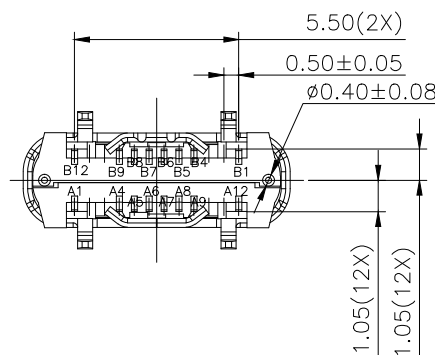
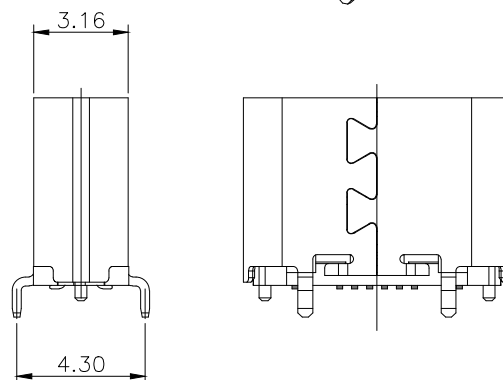
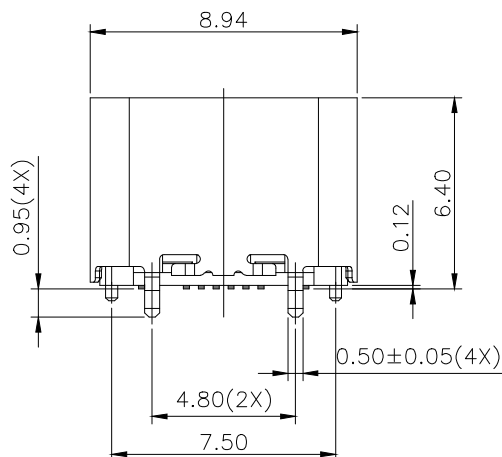
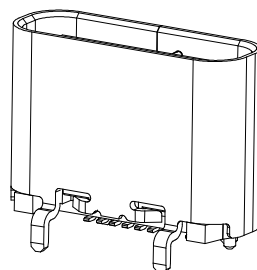
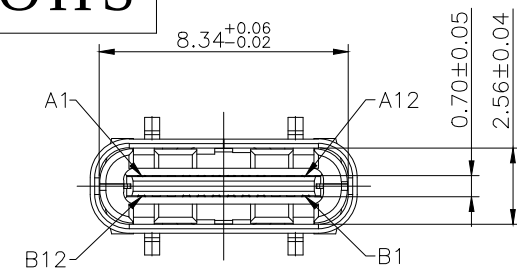


ROHS



NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING:LCP,UL94 V=0.
2.TERMINAL: COPPER ALLOY(C1814)
3.MID PLATE: STAINLESS STEEL(SUS301)
4.FRONT SHELL: STAINLESS STEEL(SUS304)

2.PLATING SPECIFICATION:

- 2-1.TERMINAL:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

- Ni 50u" MIN. UNDER PLATED OVER ALL.

2-3.MID PLATE:

CLEAR ONLY

3. MECHANICAL PERFORMANCE.

- 3-1.INSERTION FORCE: 0.5~2.0kgf.
3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
3-3.DURABILITY: 10000 CYCLES.

4. ELECTRICAL PERFORMANCE.

- 4-1. VOLTAGE RATING:5 V DC/AC (RMS. max)
CURRENT RATING:5 AMPS. FOR TOTAL VBUS/GND PINS;
1.25AMPS FOR CC PIN,0.25 AMPS. FOR ALL OTHER CONTACT.

- 4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.

- 4-3.INSULATION RESISTANCE: 100MΩ MIN
4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

- OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

<i>PIN</i>	<i>SIGNAL NAME</i>
A1	GND
A4	V _{Bus}
A5	CC1
A6	D _p 1
A7	D _n 1
A8	SBU1
A9	V _{Bus}
A12	GND

<i>PIN</i>	<i>SIGNAL NAME</i>
B12	GND
B9	V _{Bus}
B8	SBU2
B7	D _n 2
B6	D _p 2
B5	CC2
B4	V _{Bus}
B1	GND

RECOMMENDED PCB LAYOUT(TOP VIEW)

THICKNESS $0.8 \pm 0.10 \text{MM}$; DEFAULT TOLERANCE: ± 0.05

APPROVALS		DATE		LCZY ELECTRONICS(SHEN ZHEN)CO.,LTD		
DRAWN	S.L.L	2019.10.12				
CHECKED				TITLE:	USB CONNECTOR	
APPROVALS				PART NO.	TYPE-C-31-D-06	
TOLERANCES ARE	30~以上	±0.30	ANGLE ±2°	UNIT: mm	SCALE: 1:1	PROJ: 
	10~30	±0.25		DRAWING NO.	_____	SHEET 1 OF 1
	5~10	±0.20				
	~ 5	±0.15				

	A		NEW			
ECN NO.	REV.	DATE.	DESCRIPTION.	CHANGE.	CHECK.	APPRO